Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	C1, C2	2	1µF	_	_	Ceramic, 6.3V, ±10%	_	0.6 x 0.3 (0201)
2	U1	1	_	TCR3UGxxx	TOSHIBA		WCSP4F	0.645 x 0.645

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